

ABSTRACT

Disclosed are a resin composition for encapsulating a semiconductor containing a phenol resin (A), an epoxy resin (B) and an inorganic filler (C), wherein the phenol resin (A) contains a polymer (a1) having a structure represented by the general formula (1), and the epoxy resin (B) contains at least one kind of epoxy resin selected from the group consisting of a triphenol methane type epoxy resin, a naphthol type epoxy resin and a dihydroanthracene type epoxy resin, and a semiconductor device, obtained by encapsulating a semiconductor element with a cured product of the resin composition for encapsulating a semiconductor.